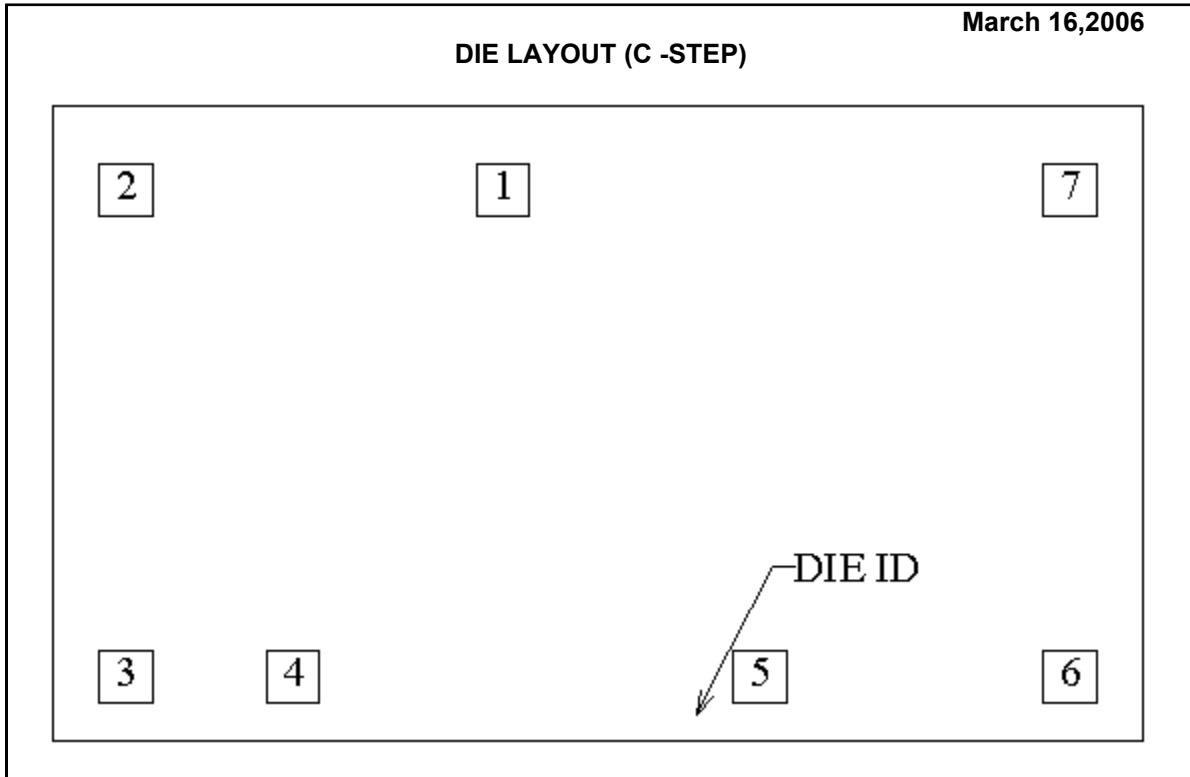


**LF156 MD8 MW8  
JFET INPUT OPERATIONAL AMPLIFIERS**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	156C	Bond Pad Opening Size (min)	91 $\mu$ m x 91 $\mu$ m
Die Step	C	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1880 $\mu$ m x 1092 $\mu$ m 74.0mils x 43.0mils	Back Side Connection	Floating
Thickness	330 $\mu$ m Nominal		
Min Pitch	287 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) <b>NC</b> = No Connection, <b>N.U.</b> = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
Balance	1	-163	402	91	x	91
IN-	2	-813	402	91	x	91
IN+	3	-813	-436	91	x	91
V-	4	-526	-436	91	x	91
Balance	5	279	-436	91	x	91
Output	6	813	-436	91	x	91
V+	7	813	402	91	x	91

**LF156 MD8 MW8**  
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